CHIPS INC.COM WAFER/DIE PROCESSING QUOTE QUESTIONNAIRE (REV. 5)

Date ______________________________

Quote No. ______________________________

Customer ______________________________

Cust. Part No./Rev. Level ________________

Geometry Available? Yes_______ No_______

1) Device Type:

Diode? _______ Transistor? _______

I.C.? _______ Other? Explain__________

____

2) Wafer Material:

Silicon? _______ Gallium Arsenide? ________

Other? ________ Specify ________________

Is wafer bumped? _________________________

Is the wafer gold backed? Yes _____ No ________

Other backside metallization ________________

3) Product Form:

Un-sawn wafer ___________________________

Wafer sawn on tape and frame ______________

# of wafers _________ # of die/wafer________

Wafer size? _________ Thickness? _________

Die size? ______________________________

Are the die in vials? _______ Vial qty ___________

Die size? ______________________________

Thickness? ______________________________

Offering Unparalleled Wafer to Die Processing

4) Wafer Process:

Is wafer thinning required? ___________________

Starting thickness? __________________________

Final thickness? _____________ +/-_____________

Thinning finish preferred:

(40-60 micron) Standard ______________

Polished Mirror finish ________________

Is wafer sawing required? Yes_______ No________

Street width? _______ Cut tolerance +/- ? ________

What is the blade and blade size currently used?

____

Current cutting speed? ________________________

What type and thickness of tape is currently used?

____

Sort and load die? ___________________________

Return on customer frame? ____________________

Return on CHIPS' frame? ______________________

5) Sort/Load:

Is orientation required? ___________________

Containers: Customer supplied? _______________

CHIPS supplied? ____________________

Which tray pack do you prefer?

Tray pack no. ________________________________

Which gel pack do you prefer?

Gel pack no. _________________________________

Would you prefer tape and reel? _______________

Do you need wafer map decoding? ______________

6) Visual Inspection Required?

100% visual? ____ 1% AQL ____ No insp. reqd. ______

MIL visual? __________ Meth. 2010 Level _______

Meth. 2070, 2072 _______ Meth. 2073 ______

Commercial visual? ______ Customer spec? ________

Spec no./Rev. level _________________(Send copy)

7) Labeling

Label each tray or gel pack? ____________________

Label shipping bags only? ______________________

8) Required Delivery

24 Hour ______ 2-3 Days ______ 1 Week ________

Other ______________________________________

What is the actual delivery date required?

____

Please fax this questionnaire to: CHIPS Inc. at 978-535-6450 or e-mail through our web site at www.chips-inc.com

9) FOR CHIPS INTERNAL USE ONLY

Current Lead Time:

Wafer Thinning ______________

Sawing ______________

Processing ______________

Visual ______________

Total Lead Time ______________

Actual Projected Ship Date

____